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A probe method of this invention includes a step of reducing an electrode (P) of a wafer (W) by using a forming gas, and a step of bringing the electrode (P) and a probe pin (14A) into contact with each other in a dry atmosphere. The probe method further includes, prior to a reducing process of an electrode (P) of the object (W') to be tested, placing the object (W') to be tested in an inert gas atmosphere and heating the object (W') to be tested. The reducing process is performed by bringing a reducing gas into contact with the electrode (P) of the object (W') to be tested under atmospheric pressure.